

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Atty. Docket

NICOLAAS J.A. VAN VEEN ET AL

NL 010069

Serial No.

Group Art Unit

Filed: CONCURRENTLY

Ex.

Title: METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE AND A
SEMICONDUCTOR DEVICE OBTAINED BY MANES OF SAID METHOD

Commissioner for Patents
Washington, D.C. 20231

4/4 Rel. andt. A
E. Willis
5-29-02

PRELIMINARY AMENDMENT

Sir:

Prior to calculation of the filing fee and examination, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend the claims as follows:

A1 3. (amended) A method as claimed in claim, characterized in that prior to the formation of the electrically conductive vias (5) and prior to the provision of the semiconductor body (1) on the flexible foil (6) that is detachably secured to the substrate (7), the flexible foil (6) is detachably secured, on the side of the insulating layer (3), to another substrate (9), after which the conductor pattern (4) is formed in the conductive layer (4),